Tarik Omer Ogurtani

List of Publications by Year
in descending order

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18	207	1163117 8	996975 15
papers	citations	h-index	g-index

18	18	18	77
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Effects of anisotropic surface drift diffusion on the strained heteroepitaxial nanoislands subjected to electromigration stressing. Journal of Applied Physics, 2022, 131, 075301.	2.5	1
2	Mesoscopic irreversible thermodynamics of morphological evolution kinetics of helical conformation in bioproteins â€˜DNAâ€™ under the isothermal isobaric conditions. , 2020, 4, 009-019.		2
3	Grain boundary grooving in bi-crystal thin films induced by surface drift-diffusion driven by capillary forces and applied uniaxial tensile stresses. Philosophical Magazine, 2012, 92, 804-829.	1.6	8
4	Mesoscopic nonequilibrium thermodynamics treatment of the grain boundary thermal grooving induced by the anisotropic surface drift diffusion. Journal of Materials Science, 2011, 46, 6054-6064.	3.7	6
5	Morphological evolution in a strained-heteroepitaxial solid droplet on a rigid substrate: Dynamical simulations. Journal of Applied Physics, 2010, 108, .	2.5	8
6	Generic role of the anisotropic surface free energy on the morphological evolution in a strained-heteroepitaxial solid droplet on a rigid substrate. Journal of Applied Physics, 2010, 108, .	2.5	6
7	Thermal grain-boundary grooving in bicrystal thin solid films having strong anisotropic surface Gibbs free energy represented by the modified cycloid-curtate function. Journal of Crystal Growth, 2009, 311, 1584-1593.	1.5	7
8	Cathode edge displacement by voiding coupled with grain boundary grooving in bamboo like metallic interconnects by surface drift-diffusion under the capillary and electromigration forces. International Journal of Solids and Structures, 2008, 45, 921-942.	2.7	9
9	Morphological evolution of voids by surface drift diffusion driven by capillary, electromigration, and thermal-stress gradients induced by steady-state heat flow in passivated metallic thin films and flip chip solder joints. I. Theory. Journal of Applied Physics, 2008, 104, 023521.	2.5	14
10	Morphological evolution of edge-hillocks on single-crystal films having anisotropic drift-diffusion under the capillary and electromigration forces. Thin Solid Films, 2007, 515, 2974-2983.	1.8	8
11	Unified theory of linear instability of anisotropic surfaces and interfaces under capillary, electrostatic, and elastostatic forces: The regrowth of epitaxial amorphous silicon. Physical Review B, 2006, 74, .	3.2	22
12	Variational formulation of irreversible thermodynamics of surfaces and interfaces with grain-boundary triple-junction singularities under the capillary and electromigration forces in anisotropic two-dimensional space. Physical Review B, 2006, 73, .	3.2	16
13	Computer Simulations on the Grain Boundary Grooving and Cathode Edge Displacement in Bamboo-like Metalic Interconnects. Materials Research Society Symposia Proceedings, 2006, 914, 1.	0.1	1
14	Mesoscopic nonequilibrium thermodynamics of solid surfaces and interfaces with triple junction singularities under the capillary and electromigration forces in anisotropic three-dimensional space. Journal of Chemical Physics, 2006, 124, 144706.	3.0	31
15	Irreversible thermodynamics of triple junctions during the intergranular void motion under the electromigration forces. International Journal of Solids and Structures, 2005, 42, 3918-3952.	2.7	35
16	The Effect of Initial Void Configuration on the Morphological Evolution Under the Action of Normalized Electron Wind Forces. Materials Research Society Symposia Proceedings, 2001, 714, 921.	0.1	0
17	Void Intergranual Motion Under the Action of Electromigration Forces in Thin Film Interconnects with Bamboo Structure. Materials Research Society Symposia Proceedings, 2001, 695, 1.	0.1	4
18	Computer simulation of void growth dynamics under the action of electromigration and capillary forces in narrow thin interconnects. Journal of Applied Physics, 2001, 90, 1564-1572.	2.5	29